

APGF0607G32B33R23-05

0.65 x 0.65 x 0.25 mm Full-Color Surface Mount LED

DESCRIPTIONS

- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode
- The Blue source color devices are made with InGaN Light Emitting Diode
- The Hyper-Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode
- Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- All devices, equipments and machineries must be electrically grounded

FEATURES

- 0.65 mm x 0.65 mm SMD LED, 0.25 mm thickness
- Low power consumption
- Can produce any color in visible spectrum
- Package: 4000 pcs / reel
- Moisture sensitivity level: 3
- Halogen-free
- RoHS compliant

APPLICATIONS

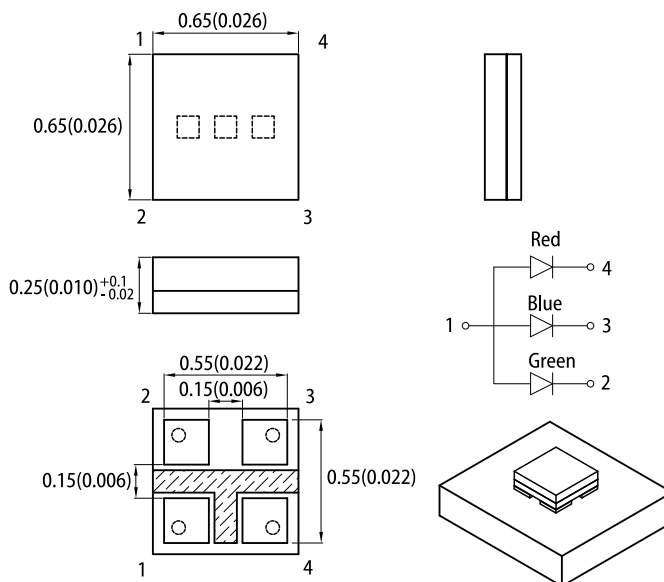
- Backlight
- Status indicator
- Home and smart appliances
- Wearable and portable devices
- Healthcare applications

ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices

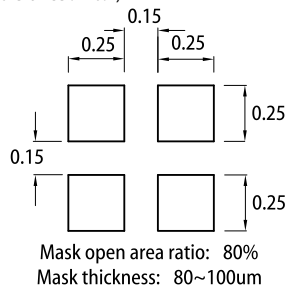


PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units : mm; tolerance : ± 0.1)



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.1 (0.004") unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 5mA ^[2]		Viewing Angle ^[1]
			Min.	Typ.	2θ1/2
APGF0607G32B33R23-05	Green (InGaN)	Water Clear	120	250	140°
	Blue (InGaN)		20	50	
	Hyper Red (AlGaInP)		15	30	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous flux: $\pm 15\%$.
3. Luminous intensity value is traceable to CIE127-2007 standards.

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		Unit
			Typ.	Max.	
Wavelength at Peak Emission I _F = 5mA	λ_{peak}	Green Blue Hyper Red	519 460 632	-	nm
Dominant Wavelength I _F = 5mA	$\lambda_{\text{dom}}^{[1]}$	Green Blue Hyper Red	524 467 624	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 5mA	$\Delta\lambda$	Green Blue Hyper Red	35 25 20	-	nm
Forward Voltage I _F = 5mA	V _F ^[2]	Green Blue Hyper Red	2.85 2.9 1.95	3.3 3.3 2.3	V
Reverse Current (V _R = 5V)	I _R	Green Blue Hyper Red	-	10 10 10	μA
Temperature Coefficient of λ_{peak} I _F = 5mA, -10°C ≤ T ≤ 85°C	TC _{λ_{peak}}	Green Blue Hyper Red	0.05 0.04 0.13	-	nm/°C
Temperature Coefficient of λ_{dom} I _F = 5mA, -10°C ≤ T ≤ 85°C	TC _{λ_{dom}}	Green Blue Hyper Red	0.04 0.03 0.02	-	nm/°C
Temperature Coefficient of V _F I _F = 5mA, -10°C ≤ T ≤ 85°C	TC _V	Green Blue Hyper Red	-2.2 -1.9 -1.8	-	mV/°C

Notes:1. The dominant wavelength (λ_d) above is the setup value of the sorting machine. (Tolerance λ_d : ±1nm.)

2. Forward voltage: ±0.1V.

3. Wavelength value is traceable to CIE127-2007 standards.

4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

Parameter	Symbol	Value			Unit
		Green	Blue	Hyper Red	
Power Dissipation	P _D	34	35	24	mW
Reverse Voltage	V _R	5	5	5	V
Junction Temperature	T _j	115	115	115	°C
Operating Temperature	T _{op}	-40 to +85			°C
Storage Temperature	T _{stg}	-40 to +100			°C
DC Forward Current	I _F ^[1]	10	10	10	mA
Peak Forward Current	I _{FP} ^[2]	25	25	30	mA
Electrostatic Discharge Threshold (HBM)	-	2000	2000	3000	V
Thermal Resistance (Junction / Ambient)	R _{th JA} ^[3]	670	590	650	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[3]	590	510	540	°C/W

Notes:

1. The maximum ratings are valid for the case of lighting a single chip

When two chips are lit at the same time, each chip should be driven at a current lower than 50% of the absolute maximum ratings

When three chips are lit at the same time, each chip should be driven at a current lower than 30% of the absolute maximum ratings

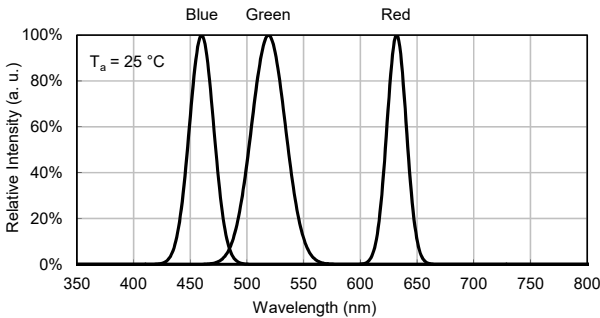
2. Duty Cycle ≤ 1/20, Pulse Width = 1ms.

3. R_{th JA}, R_{th JS} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad).

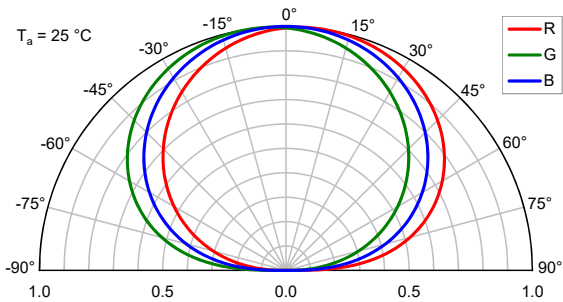
4. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

TECHNICAL DATA

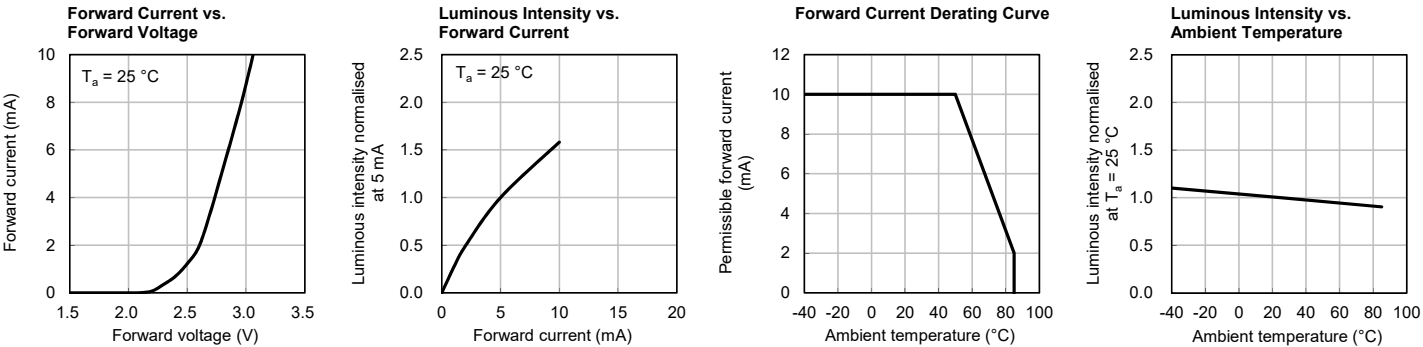
RELATIVE INTENSITY vs. WAVELENGTH



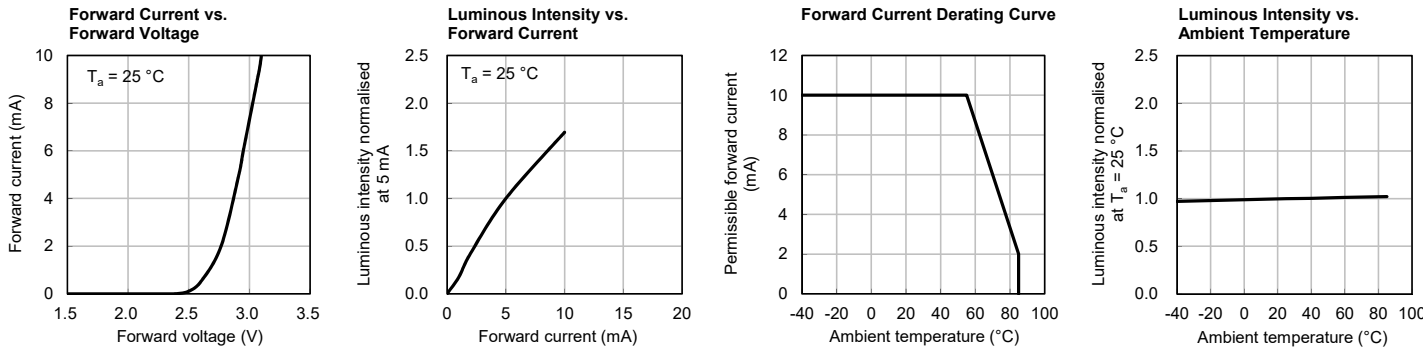
SPATIAL DISTRIBUTION



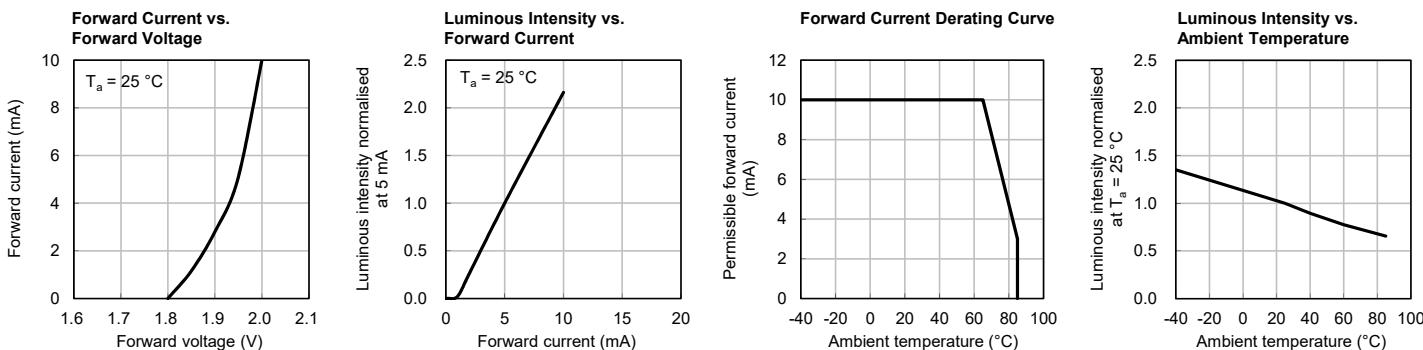
GREEN



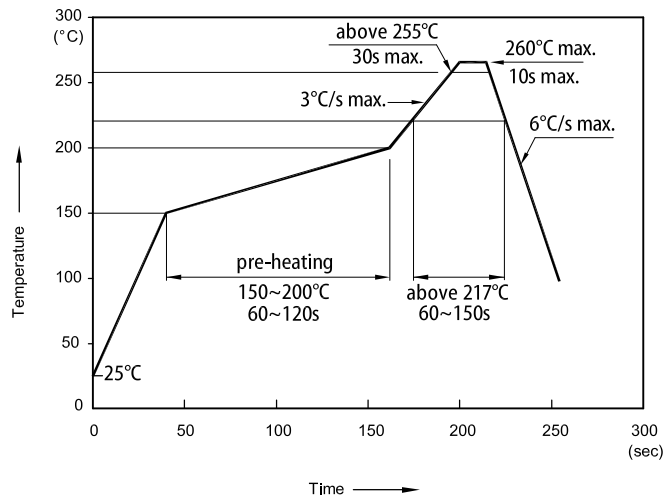
BLUE



HYPER RED



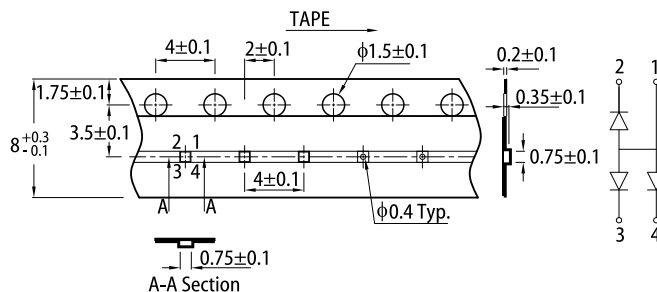
REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



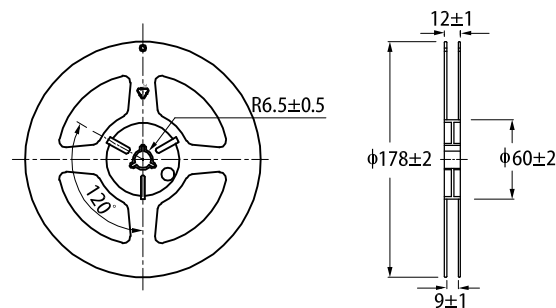
Notes:

1. Don't cause stress to the LEDs while it is exposed to high temperature.
2. The maximum number of reflow soldering passes is 2 times.
3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

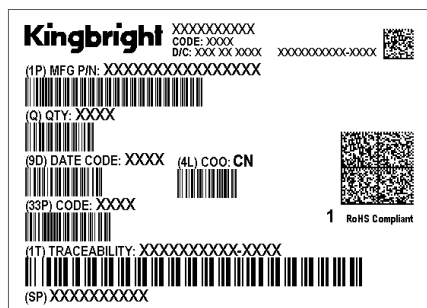
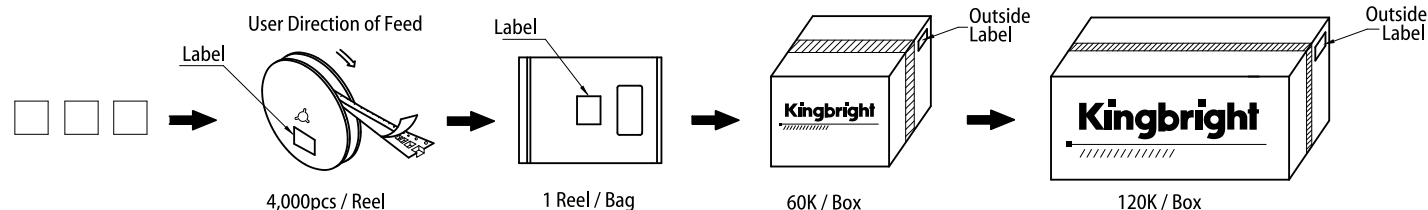
TAPE SPECIFICATIONS (units : mm)



REEL DIMENSION (units : mm)



PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
4. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.
5. The contents and information of this document may not be reproduced or re-transmitted without permission by Kingbright.
6. All design applications should refer to Kingbright application notes available at <https://www.KingbrightUSA.com/ApplicationNotes>